

Introduction of "Standardized IC Socket for BGA/LGA Packages"

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■ Summary

Yokowo has launched "Standardized IC Socket for BGA (Ball Grid Array) and LGA (Land Grid Array) Packages" that is one of main products of circuit test connector business sector.

■ Background

Yokowo has a long time experience for manufacturing and development of IC sockets for BGA /LGA Packages. For IC Socket business, especially, fast turnaround time and lower price are becoming more important, however, in many cases, IC sockets are custom made and fabricated by machine one by one due to small volume, so that it is difficult to meet these market requirements.

In order to fulfill with market requirement, Yokowo standardizes the socket design that occupies majority of its cost and launches New IC Socket.

This standardized socket can reduce design lead-time dramatically and also keeping components in stock shortens lead-time of assembly. As result, turnaround time and cost of the socket cut by a half compare to a conventional socket.

(Conventional socket: 3 weeks ARO -> Standardized socket: 1.5 weeks ARO)

■ Outline of Standardized IC Socket for BGA/LGA Packages

• Specifications

Package type	BGA or LGA
Pitch size	0.8mm available (0.65mm, 0.5mm, 0.4mm planned)
Package size	24mm × 24mm
Pad area	21.6mm × 21.6mm(28 in line × 28 in row for 0.8mm pitch)
Socket size	42mm × 42mm
Socket type	Open top or Clamshell
Placement	with guide plate or with floating plate
PCB positioning	32mm to 34mm
Operating temperature	-30 to +125 degree C
Current	1A



■ Future Plan

Yokowo introduces this Standardized IC Socket targeted to the Logic IC makers worldwide and plans to produce 100sets per month to start.

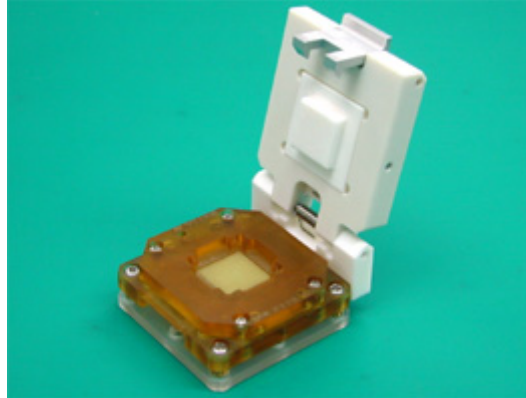


Photo: Standardized IC Socket for BGA/LGA Packages

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